TSF-6522 No-Clean Tacky Soldering Flux

Product Description

Kester formula TSF-6522 is a no-clean tacky soldering flux formula designed to be used with a rotating disc, a doctor blade, or a drum fluxer. The TSF-6522 can also be used in dot dispensing for BGA/PGA sites or in a rework application for surface mount TSF-6522 maintains its activity packages. and dispensing characteristics for up to 8 hours and can be used in a wide range of temperature and humidity conditions. Kester maintains highest standards the manufacturing TSF-6522 the under vacuum environment.

- High tack values and long tack life
- Leaves bright/shiny solder joints after reflow
- ANSI/J-STD-004 flux designator ROL0
- Can reflow in air or nitrogen environments

Physical Properties (typical)

• Viscosity: 285 poise Kester Method #1W-QC-3-09

• Tackiness (grams-force): 100 Kester Method #1W-QC-03-04

• Acid Number: 75.4 Kester Method #1W-QC-G-01

• Color: Yellow to Light Amber Kester Method #1W-QC-G-18

• Copper Mirror Corrosion: Low

Tested to J-STD-004, IPC-TM-650, Method 2.3.32

• Corrosion Test: Low

Tested to J-STD-004, IPC-TM-650, Method 2.6.15

• pH 5% Solution: 7.7 Kester Method #1W-QC-G-15

Qualitative Halide Tests:

• Silver Chromate: Pass

Tested to J-STD-004, IPC-TM-650, Method 2.3.33

• Fluorides by Spot Test: Pass Tested to J-STD-004, IPC-TM-650, Method 2.3.35.1

• Typical S.I.R., IPC:

Tested to J-STD-004, IPC-TM-650, Method 2.6.3.3, (B-24 coupon)

Blank at 24 hours: 3.08 x 10¹⁰ ohms Blank at 96 hours: 1.27 x 10¹⁰ ohms Blank at 168 hours: 8.79 x 10⁹ ohms

Uncleaned at 24 hours: 2.56 x 10⁸ ohms Uncleaned at 96 hours: 4.17 x 10⁸ ohms Uncleaned at 168 hours: 6.38 x 10⁸ ohms

• Typical S.I.R., Bellcore:

Tested to TR-NWT-000078, IPC B-24 coupon

Blank at 24 hours: 1.44 x 10¹² ohms Blank at 96 hours: 1.38 x 10¹³ ohms

Uncleaned at 24 hours: 2.19 x 10¹³ ohms Uncleaned at 96 hours: 1.56 x 10¹³ ohms

Reliability Properties (typical)

KESTER SOLDER

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The data and recommendations presented are based on tests which we consider reliable. Because Kester Solder has no control over the conditions of use, we disclaim any responsibility connected with the use of any of our products or the information presented. We advise that all chemical products be used only by or under the direction of technically qualified personnel who are aware of the potential hazards involved and the necessity for reasonable care in their handling.

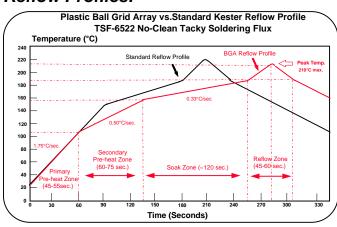
BRANCHES: ANAHEIM, CA • JAMESTOWN, NY
BRANTFORD, ONTARIO, CANADA • SINGAPORE • GERMANY • TAIWAN

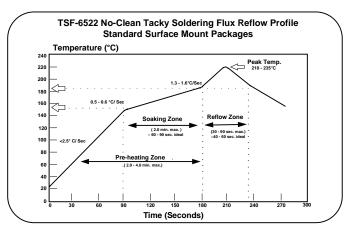
Standard Applications:

- Works on flip chip, chip scale package and flip chip bumping sites assemblies as a soldering flux.
- Tacky solder flux formulations are designed for pin transfer, dot dispensing and/or syringe applications.
- Tacky solder flux formulations can be used as a tack and flux vehicle for soldering components to a solid solder deposit (SSD), or precision pad technology (PPT) board surfaces.
- Great for rework applications on all PCB packages.
- Can be used in BGA/PGA sphere/pin attachment vehicle or for repair and reballing/repinning.

Application Notes

Reflow Profiles:





Printing Parameters:

• Temperature/Humidity -- Optimal ranges for production are 21-25°C (70-77°F) and 35-65% R.H.

Activation Parameters:

Temperature -- Optimal activation temperatures are 130°-185°C (266-365°F). See "Soak Zone" in diagrams above.

Cleaning:

- Formula TSF-6522 is a no-clean formula. The residues do not need to be removed for typical applications.
- Although formula TSF-6522 is designed for no-clean applications, its residues can be easily removed using automated cleaning equipment (in-line or batch) with the aid of Kester Bio-Kleen #5768 saponifier in a 10-12% concentration in de-ionized water at approximately 140°F (60°C).

Available Packaging:

- Syringes -- 10 gram (10cc) and 30 gram (30cc) syringes available.
- Cartridges -- 150 gram and 300 gram cartridges available.
- Jars -- 50 gram and 100 gram jars available.

Storage, Handling, and Shelf Life:

- Storage & Handling -- should be kept at standard refrigeration temperatures and humidity conditions, 0-10°C (32-50°F) and 35-55% R.H. respectively.
- Shelf life -- 4 months from date of manufacture when held at 0-10°C (32-50°F).

Health & Safety:

- This product, during handling or use, may be hazardous to health or the environment.
- Read the Material Safety Data Sheet and warning label before using this product.

Attention Specification Writers:

- The technical information contained herein is consistent with the properties of this material but should not be used in the preparation of specifications as it is intended for reference only.
 For assistance in preparing specifications, please contact your local Kester Solder office for details.

24 Nov 98/TJT/dms